

Form PTO 1449 (Modified)		U.S. DEPARTMENT OF COMMERCE PATENT AND TRADEMARK OFFICE		ATTY DOCKET NO. <b>245959US2</b>		SERIAL NO. <b>NEW APPLICATION</b>	
LIST OF REFERENCES CITED BY APPLICANT				APPLICANT <b>Masakiyo MATSUMURA, et al.</b>			
				FILING DATE <b>HEREWITH</b>		GROUP	
<b>U.S. PATENT DOCUMENTS</b>							
EXAMINER INITIAL	AA	DOCUMENT NUMBER	DATE	NAME	CLASS	SUB CLASS	FILING DATE IF APPROPRIATE
	AB						
	AC						
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	AN						
<b>FOREIGN PATENT DOCUMENTS</b>							
		DOCUMENT NUMBER	DATE	COUNTRY	TRANSLATION YES NO		
	AO						
	AP						
	AQ						
	AR						
	AS						
	AT						
	AU						
<b>OTHER REFERENCES (Including Author, Title, Date, Pertinent Pages, etc.)</b>							
<b>RK</b>	AV	Masakiyo MATSUMURA, "Preparation of Ultra-Large Grain Silicon Thin-Films by Excimer-Laser", SURFACE SCIENCE, Vol. 21, No.5, March 2000, pp. 278-287					
<b>RK</b>	AW	M. NAKATA, et al., "Two-Dimensionally Position-Controlled Ultra-Large Grain Growth Based on Phase-Modulated Excimer-Laser Annealing Method", ELECTROCHEMICAL SOCIETY PROCEEDINGS, Vol. 2000-31, pgs.148-153					
<b>RK</b>	AX	Mitsuru NAKATA, et al., "A New Nucleation-Site-Control Excimer-Laser-Crystallization Method", JAPANESE JOURNAL OF APPLIED PHYSICS, PART 1 REGULAR PAPERS, SHORT NOTES & REVIEW PAPERS, Vol. 45 No. 5A, May 2001, pgs. 3049-3054					
<b>RK</b>	AY	Chang-Ho OH, "Optimization of phase-modulated excimer-laser annealing method for growing highly-packed large-grains in Si thin-films, APPLIED SURFACE SCIENCE 154-155, 2000, pgs. 105-111					
<b>RK</b>	AZ	M. MATSUMURA, "Advanced Laser-Crystallization Technologies of Si for High-Performance TFTs, ALTEDEC, pgs. 263-266					
					<input type="checkbox"/> Additional References sheet(s) attached Date Considered <b>06/12/2006</b>		
Examiner <b>/Robert Kunemund/</b>							
*Examiner: Initial if reference is considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.							